

AMENDMENTS TO THE SPECIFICATION

The paragraph beginning on page 30, line 21, is being amended as follows:

The measurement of molecular orientation and that of linear expansion coefficient were performed on ~~an inflation~~ a T die molding film (thickness: 25 μm) manufactured according to the process described in Example 1 of JP-A-Hei9-286907. Also, a print circuit board was prepared and evaluated in manners similar to that in Example 3 for a glass epoxy substrate 1 heat-pressed with the film at 320°C.50 kg/cm² for 10 minutes.